

Appln No. 10/712,364  
Amdt date October 13, 2005  
Reply to Office action of August 18, 2005

**REMARKS/ARGUMENTS**

Reconsideration of the application is respectfully requested. Claims 1 - 15 pending in the application have been canceled and new Claims 16 - 21 have been added.

In the Final Office action, Claim 1 - 15 were rejected as either anticipated or obvious in view of Shigeyuki, Mulligan et al. and Hwan et al.. It is respectfully submitted that new Claims 16 -21 are not anticipated or obvious over these references.

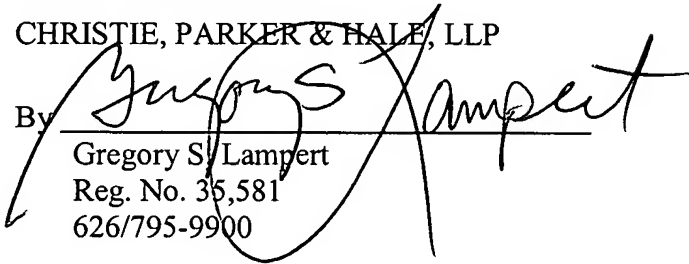
Claim 16 recites a semiconductor wafer machining method for machining a semiconductor comprising the steps of carrying out an entire cut through the semiconductor wafer with a cutting blade to form lateral surfaces and irradiating the lateral surfaces of the cut with laser light to form a modified layer by melting. Shigeyuki discloses a laser which is used to irradiate the bottom of a channel formed by a dicing blade, but not the entire lateral surface of a complete cut through the semiconductor wafer as claimed. Mulligan teaches using a laser to ablate away two trenches and after the formation of the trenches, a wafer saw cuts a channel between the first trench and the second trench through an interconnect layer and through the semiconductor wafer. The laser and the saw do not contact the same area in Mulligan. Hwan et al. simply discloses a laser sintering system for sintering the serrated edge of a die. Hwan et al. does not recite forming modified layer by melting through irradiating the lateral surface of the cut with a laser light as claimed. Sintering creates a smooth edge by heating without melting. The claims in the current application specifically recite melting.

In view of the foregoing amendments and remarks, it is respectfully submitted that the application is now in condition for allowance, and, accordingly, early indication thereof is respectfully requested.

Respectfully submitted,

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